

# RZ/T2L Group

RZ/T2L FuSa Reference Kit (CIP Safety)

# Introduction

This document is the release note of CIP safety<sup>™</sup> for operating on the RZ/T2L Functional Safety Reference Board (hereinafter referred to as RZ/T2L FuSa Kit), which is equipped with two RZ/T2L MPUs manufactured by Renesas Electronics.

# **Target Device**

RZ/T2L Group

R01AN7876JJ0100 Rev.1.00 Jun.30.2025



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### 1. Overview

CIP Safety is equipped on the RZ/T2L FuSa Reference Board manufactured by Renesas Electronics to perform CIP Safety communication.

# 2. Hardware Configuration

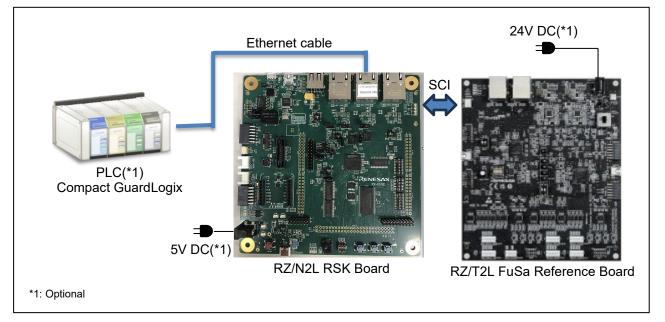


Figure 2-1 RZ/T2L FuSa Reference Kit Configuration

These boards can be purchased from the following URL.

RZ/N2L RSK Board: https://www.renesas.com/rzn2l-rsk RZ/T2L FuSa Reference Board: https://www.renesas.com/rzt2l-safety-network



### 2.1.1 Operation Environment

■RZ/T2L FuSa Reference Kit

| ltem  | Description   |  |  |
|---|---|--|--|
| Board   | RZ/T2L FuSa Reference Kit                                     |  |  |
| MPU   | RZ/T2L Group  |  |  |
|   | R9A07G074M04GBG x2 : 196pinFBGA                               |  |  |
| Operating frequency   | CPU Core : 800MHz (Arm <sup>®</sup> Cortex <sup>®</sup> -R52) |  |  |
| Operating voltage   | 3.3V/1.8V/1.1V  |  |  |
| Operating mode  | xSPI0 boot mode(x1 boot serial flash)                         |  |  |
| Device  | Serial Flash ROM (64Mbyte)                                    |  |  |
|   | Renesas Electronics AT25SF128A                                |  |  |
| ntegrated development IAR Systems                                       |   |  |  |
| environment Embedded Workbench® for Arm Version 9.20.3(Functional Safet |   |  |  |
| Emulator  | IAR Systems   |  |  |
|   | I-jet   |  |  |
| Software(*1)  | RZ/T2L CIP Safety Reference Software Ver.1.00 or later        |  |  |
|   | (P/N: RTK0EF0200F01001SJ_CI)                                  |  |  |

\*1: Download from QR code of CD-ROM included with the board.

#### ■RZ/N2L RSK Board

| ltem                               | Description  |
|------------------------------------|--|
| Board                              | RZ/N2L RSK Bard  |
| MPU                                | RZ/N2L Group   |
|                                    | R9A07G084M04GBG: 225pinFBGA  |
| Operating frequency                | CPU Core : 400MHz (Arm <sup>®</sup> Cortex <sup>®</sup> -R52)      |
| Operating voltage                  | 3.3V/1.8V/1.1V   |
| Operating mode                     | xSPI0 boot mode(x1 boot serial flash)                              |
| Device                             | Serial Flash ROM (64Mbyte)   |
|                                    | Macronix MX25UR51245GMI00  |
| Integrated development IAR Systems |  |
| environment                        | Embedded Workbench <sup>®</sup> for Arm Version 9.60.2 (FSPv2.1.0) |
|                                    | Renesas Electronics  |
|                                    | e <sup>2</sup> studio 2024-10 (FSPv2.1.0)                          |
| Emulator                           | IAR Systems  |
|                                    | I-jet  |
|                                    | Segger   |
|                                    | J-link OB  |
| Software(*2)                       | RZ/N2L EtherNet/IP OpENer Sample Program Ver.2.10 or later         |

\*2: <u>https://www.renesas.com/en/document/scd/rzn2l-group-ethernetip-opener-sample-program-package?language=en&r=1622401</u>



# ■Connecting Devices

| Item                        | Description   |
|-----------------------------|---|
| PLC programming environment | Studio 5000 Logix Designer (9324M-RLDT11M Studio 5000 Lite Edition) |
|                             | (Rockwell Automation)   |
| PLC                         | Compact GuardLogix SIL3 0.6.0,3M Motion : 5069-L306ERMS3(Rockwell   |
|                             | Automation)   |
|                             | Compact 5000 Spring RTB : 5069-RTB64-SPRING(Rockwell Automation)    |

\*: For how to get them, please contact each manufacturer.



# 2.2 RZ/T2L FuSa Reference Board Settings

Table 2-1 shows RZ/T2L FuSa Reference Board Switch Settings, and Table 2-2 shows RZ/T2L FuSa Reference Board Jumper Settings.

# Table 2-1 RZ/T2 L FuSa Reference Board Switch Setting

SW1

| 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   |
|-----|-----|-----|-----|-----|-----|-----|-----|
| OFF |

SW2

| 1   | 2   | 3   | 4   | 5   | 6   |
|-----|-----|-----|-----|-----|-----|
| OFF | OFF | OFF | OFF | OFF | OFF |

SW3

| 1   | 2   |
|-----|-----|
| OFF | OFF |

SW4

| 1   | 2   | 3   | 4   | 5   | 6   | 7   | 8   |
|-----|-----|-----|-----|-----|-----|-----|-----|
| OFF |

SW6

| 1   | 2   |
|-----|-----|
| OFF | OFF |

#### SW9-12

| Switch | Left                             | Center                                | Right                                    |
|--------|----------------------------------|---------------------------------------|--|
| Switch | Silkscreen: "LP-B"               | Silkscreen: "F"                       | Silkscreen: "-"                          |
|        | Loop-back connection             | Pseudo stuck-at fault                 | Normal connection                        |
| SW9    | RZ/T2L-B<br>TXD4<br>RXD4<br>RXD4 | RZ/T2L-B<br>Stuck at<br>"H" → RXD4    | RZ/T2L-A RZ/T2L-B<br>TXD4 RXD4           |
| SW10   | RZ/T2L-A<br>TXD4<br>RXD4         | RZ/T2L-A<br>RXD4 Stuck at<br>"H"      | RZ/T2L-A RZ/T2L-B<br>RXD4 - TXD4         |
| SW11   | RZ/T2L-B<br>GTIOC10A<br>GTETRGB  | RZ/T2L-B<br>Stuck at<br>"L" → GTETRGB | RZ/T2L-A RZ/T2L-B<br>GTIOC10A D→ GTETRGB |
| SW12   | RZ/T2L-A<br>GTIOC10A<br>GTETRGB  | RZ/T2L-A<br>GTETRGB Stuck at          | RZ/T2L-A RZ/T2L-B                        |



| SW13   |   |                     |   |
|--------|---|---------------------|---|
| Switch | Left<br>Silkscreen: SCI-CON   | Center              | Right<br>Silkscreen: T2L-B                |
|        | Connected to: CON14   | Connected to: None  | Connected to: RZ/T2L-B                    |
| SW13   | RZ/T2L-A CON14<br>TXD3<br>RXD3<br>RXD3<br>C<br>TXD3<br>C<br>TXD3<br>C<br>TXD3<br>CON14<br>CON14<br>TXD3<br>CON14<br>TXD3<br>CON14 | Setting not allowed | RZT2L-A RZT2L-B<br>TXD3 RXD3<br>RXD3 TXD3 |
|        |   |                     | 1   |

# Table 2-2 RZ/T2L FuSa Reference Board Jumper Settings

| No. | Jumper | Setting   |
|-----|--------|-----------|
| 1   | JP1    | 1-4 Short |



# 2.3 RZ/N2L RSK Board Settings

Table 2-3 shows RZ/N2L RSK Board Switch Settings and Table 2-4 shows RZN2L RSK Board Jumper Settings.

#### Table 2-3 RZ/N2L RSK Board Switch Settings

SW3

| 1   | 2   | 3   | 4   |  |
|-----|-----|-----|-----|--|
| OFF | OFF | OFF | OFF |  |

SW4

| 1  | 2  | 3  | 4  | 5   | 6   | 7   | 8   |
|----|----|----|----|-----|-----|-----|-----|
| ON | ON | ON | ON | OFF | OFF | OFF | OFF |

SW8

| 1   | 2  | 3   | 4  | 5   | 6   | 7   | 8  | 9   | 10  |
|-----|----|-----|----|-----|-----|-----|----|-----|-----|
| OFF | ON | OFF | ON | OFF | OFF | OFF | ON | OFF | OFF |

SW11

| 1  | 2   | 3   | 4   | 5   | 6   | 7   | 8  | 9   | 10  |
|----|-----|-----|-----|-----|-----|-----|----|-----|-----|
| ON | OFF | OFF | OFF | OFF | OFF | OFF | ON | OFF | OFF |

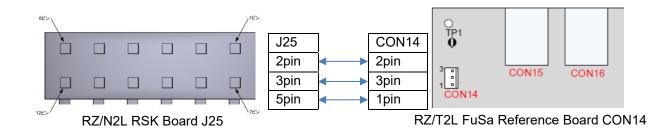
#### Table 2-4 RZ/N2L RSK Board Jumper Settings

| No. | Jumper | Setting   |  |
|-----|--------|-----------|--|
| 1   | JP9    | Open      |  |
| 2   | CN8    | 2-3 short |  |
| 3   | CN17   | 1-2 short |  |
| 4   | CN20   | 2-3 short |  |
| 5   | CN21   | 2-3 short |  |
| 6   | CN22   | 2-3 short |  |
| 7   | CN24   | 2-3 short |  |
| 8   | CN25   | 1-2 short |  |
| 9   | CN27   | 1-2 short |  |
| 10  | CN29   | 1-2 short |  |
| 11  | CN31   | 1-2 short |  |
| 12  | CN32   | 1-2 short |  |



# 2.4 RZ/T2L FuSa Reference Board and RZ/N2L RSK Board Settings

Connecting with RZ/T2L FuSa Reference Board and RZ/N2L RSK Board is shown the below.





# 3. Operating Procedure

# 3.1 How to write Program

#### ■RZ/N2L RSK Board

Refer to "Quick Start Guide: EtherNet/IP OpENer Sample Program(r01an6601)" in RZ/N2L EtherNet/IP OpENer Sample Program Package.

■RZ/T2L FuSa Reference Board

Refer to "RZ CIP Safety Reference Software Development Handbook (R30UZ0217)" in RZ/T2L CIP Safety Reference Software Package.

# 3.2 Operation

Refer to "RZ CIP Safety Reference Software Development Handbook (R30UZ0217)" in RZ/T2L CIP Safety Reference Software Package.



# **Revision History**

|      |              | Description |                      |
|------|--------------|-------------|----------------------|
| Rev. | Date         | Page        | Summary              |
| 1.00 | Jun.30. 2025 | -           | First edition issued |
|      |              |             |                      |



### General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

#### 1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power is supplied until the power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

- 6. Voltage application waveform at input pin Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V<sub>IL</sub> (Max.) and V<sub>IH</sub> (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V<sub>IL</sub> (Max.) and V<sub>IH</sub> (Min.).
- 7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

8. Differences between products

Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a systemevaluation test for the given product.

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